

IN THE SPECIFICATION

Please replace paragraph [0029] with the following paragraph.

FIGS. 4A & 4B illustrate one embodiment of solder coated non-fusible particle filler before and after reflow respectively. As shown in **FIG. 4A**, the present invention coats the highly thermally conductive non-fusible particles (particles) 402 with the good but less thermally conductive solder or solder alloy 406 prior to blending with the plastic binder (cross-hatch) 408. The coated non-fusible particles 402 and 406 can initially be in point contact 404 with each other. As shown in FIG 4A, the coated non-fusible particles 402 and 406 are of non-uniform size and randomly positioned with respect to the plastic binder 408. As shown in **FIG. 4B**, larger contact areas 410 can be formed by the solder between the particles 402 resulting from the reflow operation. The larger contact areas 410 can be larger cross-sections of continuous pathways for heat conduction. In addition, the solder contact area 410 with the particle 402 can be wetted out providing good physical contact that results in good thermal transfer across this contact area 410. With solder coated particle filler 402 and 406, the amount of filler needed to obtain an equal value of thermal conductivity for the TIM 408 is much lower than using only solder filler 406 or particle filler 402.